

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Product Summary

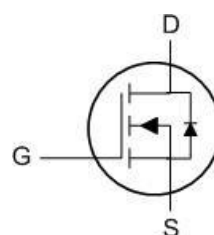
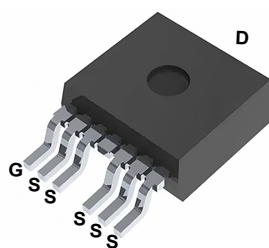


BVDSS	RDSON	ID
150V	6mΩ	150A

Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

TO263-7L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	150	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	150	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	86	A
I_{DM}	Pulsed Drain Current ²	560	A
EAS	Single Pulse Avalanche Energy ³	1105	mJ
I_{AS}	Avalanche Current	66	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation ⁴	298	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	45	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	0.42	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=250\mu A$	150	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	---	---	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V$, $I_D=60A$	---	6	7.4	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu A$	2	3	4	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	$mV/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=150V$, $V_{GS}=0V$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=150V$, $V_{GS}=0V$, $T_J=100^\circ\text{C}$	---	---	100	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5V$, $I_D=60A$	---	100.8	---	S
R_g	Gate Resistance	$V_{DS}=0V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	4	---	Ω
Q_g	Total Gate Charge	$V_{DS}=75V$, $V_{GS}=10V$, $I_D=60A$	---	74.5	---	nC
Q_{gs}	Gate-Source Charge		---	31.7	---	
Q_{gd}	Gate-Drain Charge		---	15.2	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{GS}=10V$, $V_{DD}=75V$, $R_G=2.7\Omega$, $I_D=60A$	---	19.1	---	ns
T_r	Rise Time		---	90.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	52.4	---	
T_f	Fall Time		---	82.5	---	
C_{iss}	Input Capacitance	$V_{DS}=75V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	4936	---	pF
C_{oss}	Output Capacitance		---	609	---	
C_{rss}	Reverse Transfer Capacitance		---	21	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	150	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V$, $I_S=60A$, $T_J=25^\circ\text{C}$	---	---	1.4	V
t_{rr}	Reverse Recovery Time	$I_F=17A$, $di/dt=100A/\mu s$, $T_J=25^\circ\text{C}$	---	132.7	---	nS
Q_{rr}	Reverse Recovery Charge		---	584.7	---	nC

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$
2. The EAS data shows Max. rating . The test condition is $V_{DD}=75V$, $V_{GS}=10V$, $L=0.5\text{mH}$, $I_{AS}=66A$.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Performance Characteristics

Fig 1: Output Characteristics

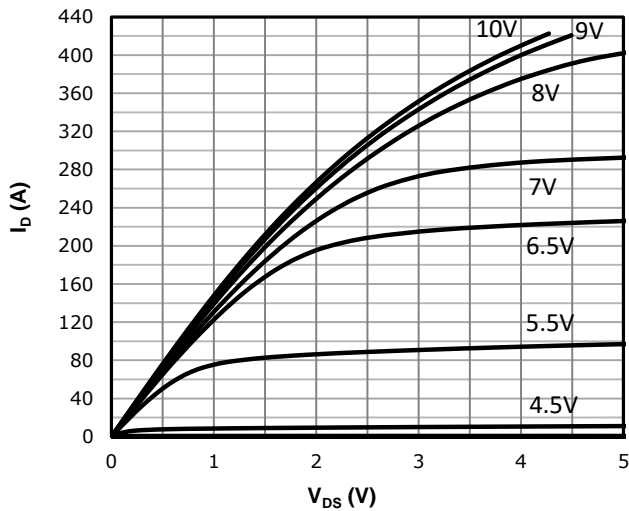


Fig 2: Transfer Characteristics

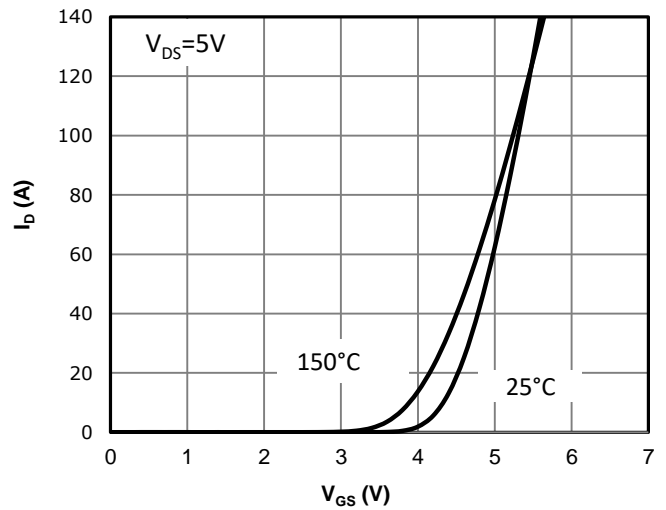


Fig 3: $R_{DS(on)}$ vs Drain Current and Gate Voltage

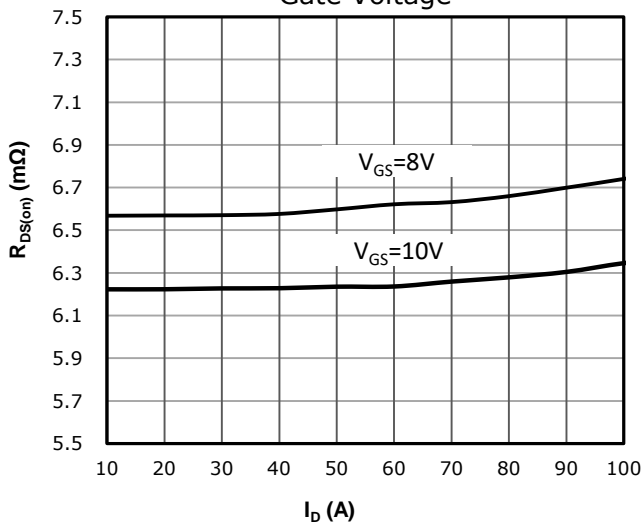


Fig 4: $R_{DS(on)}$ vs Gate Voltage

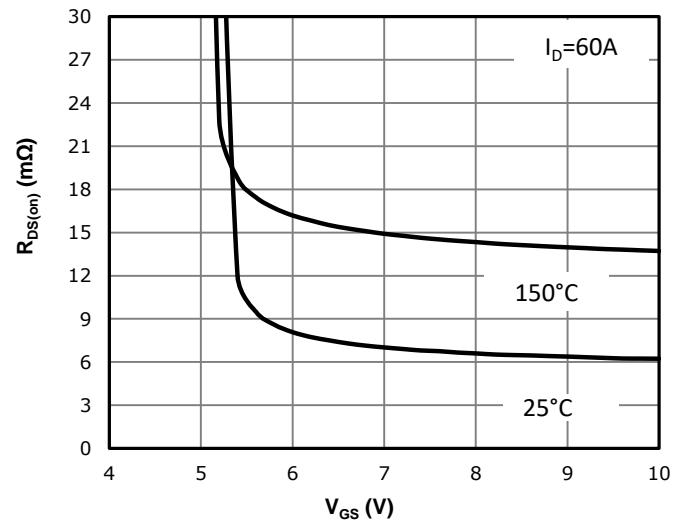


Fig 5: $R_{DS(on)}$ vs. Temperature

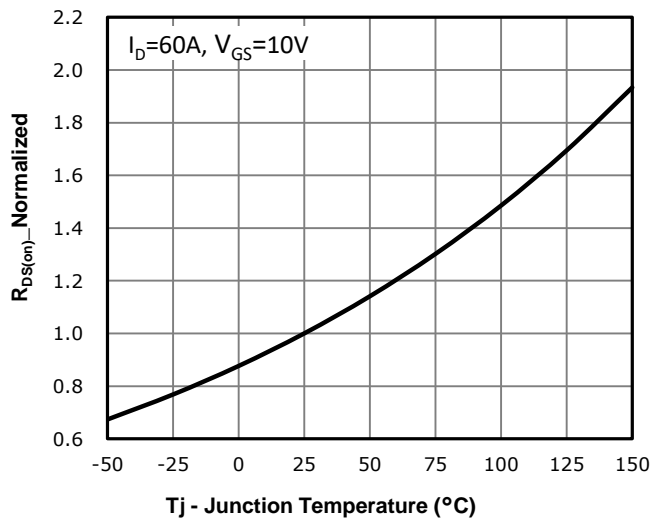


Fig 6: $V_{GS(th)}$ vs. Temperature

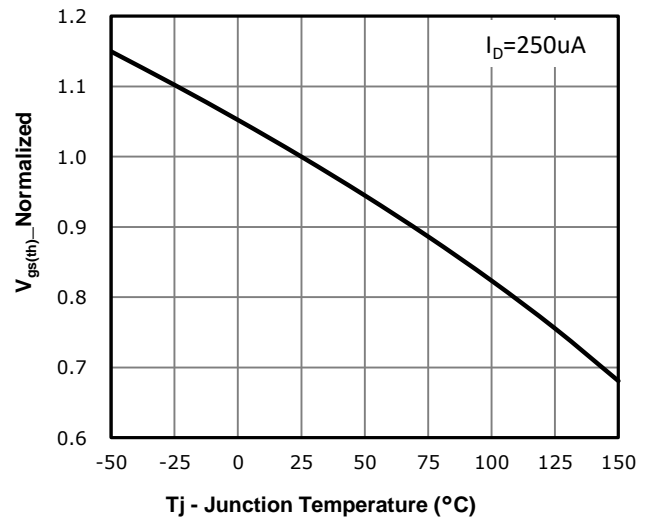


Fig 7: BVdss vs. Temperature

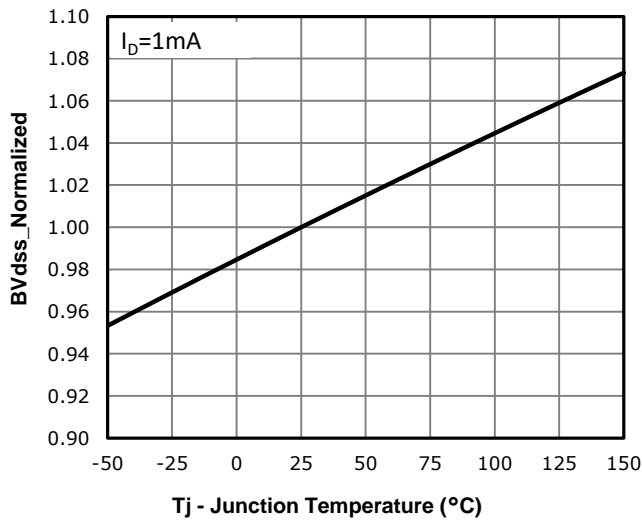


Fig 8: Capacitance Characteristics

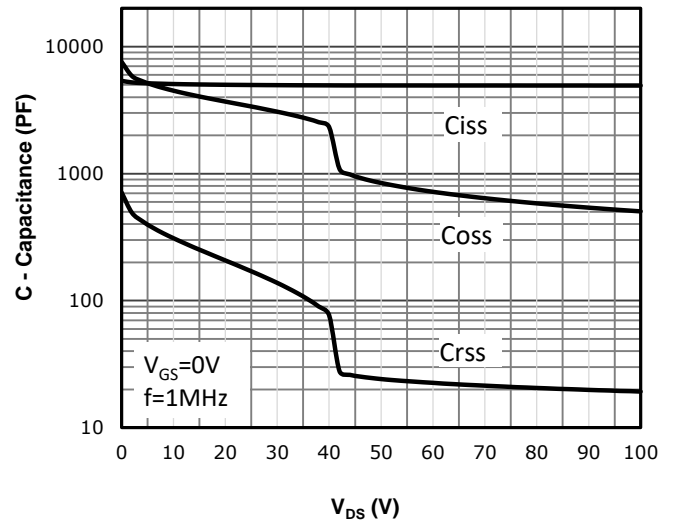


Fig 9: Gate Charge Characteristics

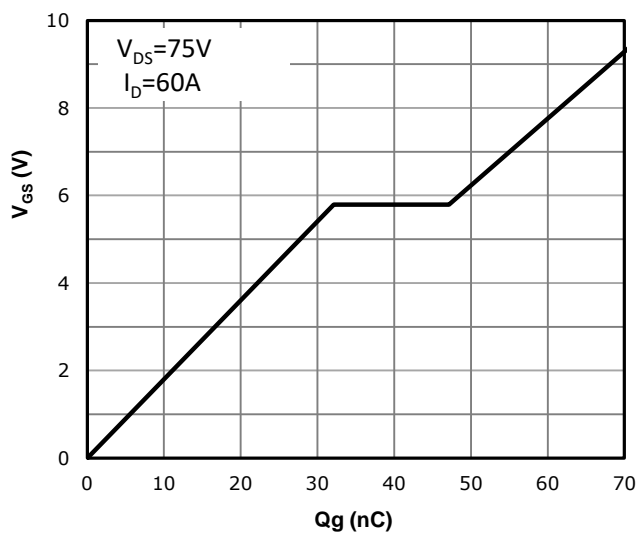


Fig 10: Body-diode Forward Characteristics

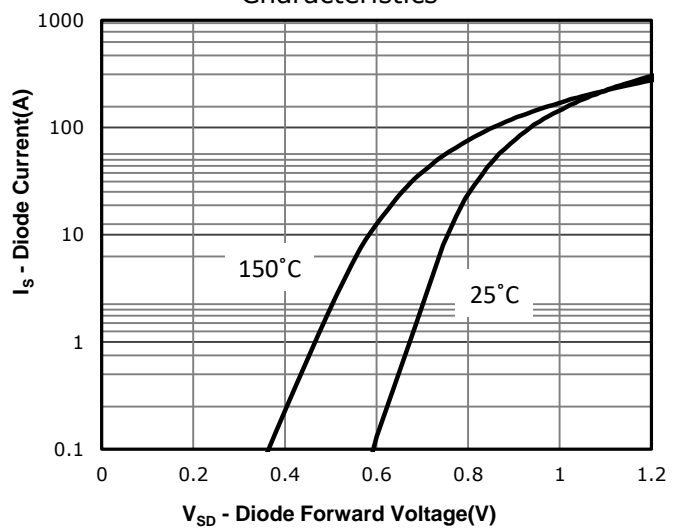


Fig 11: Power Dissipation

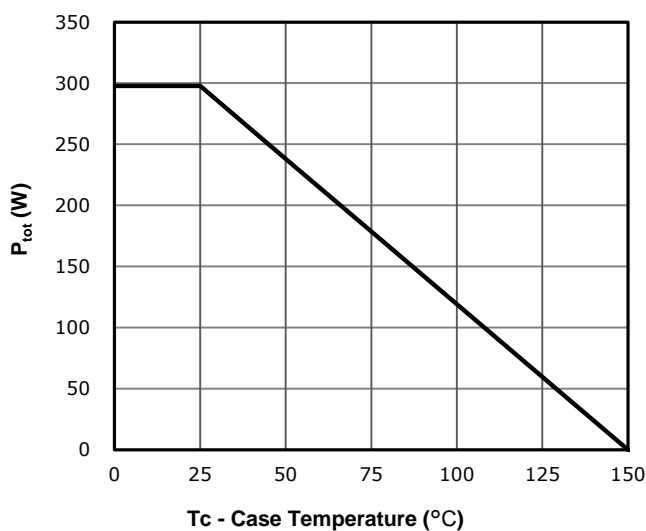


Fig 12: Drain Current Derating

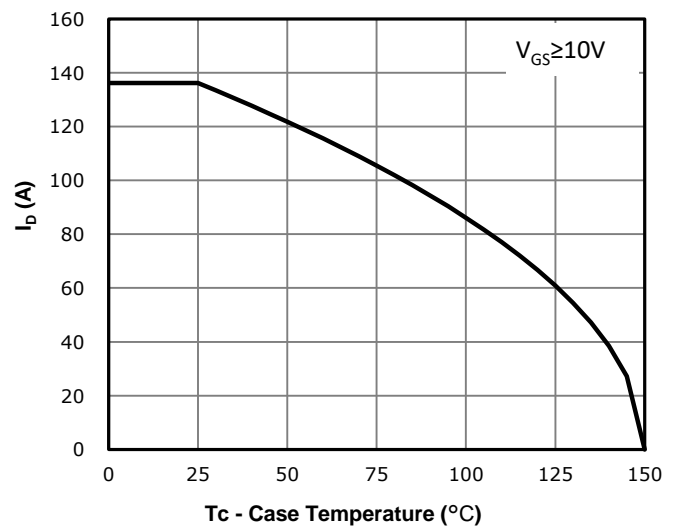


Fig 13: Safe Operating Area

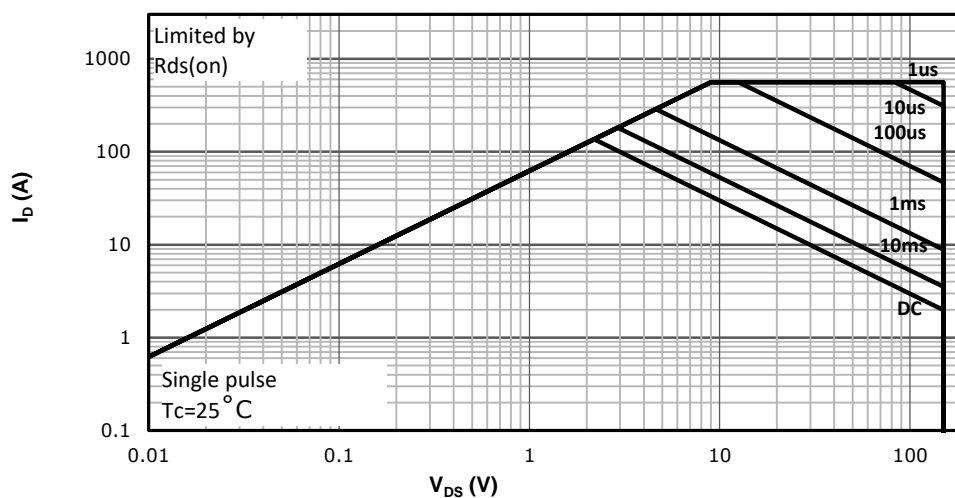
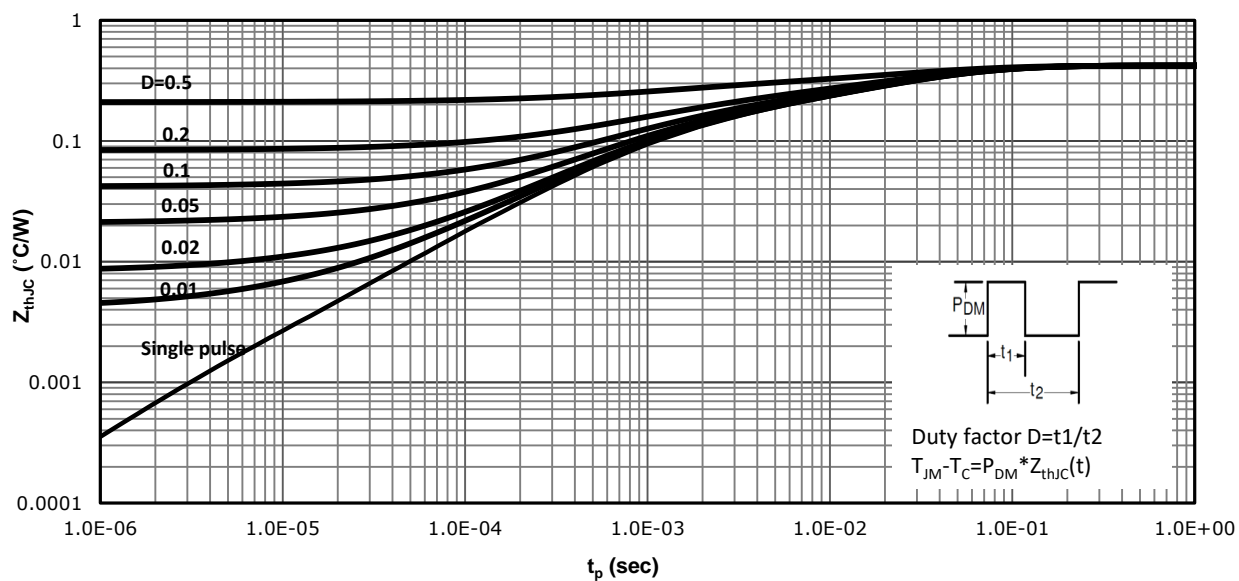
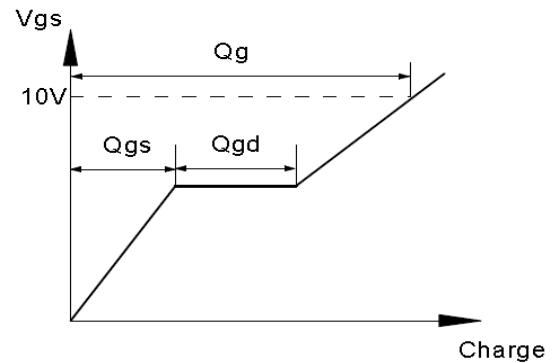
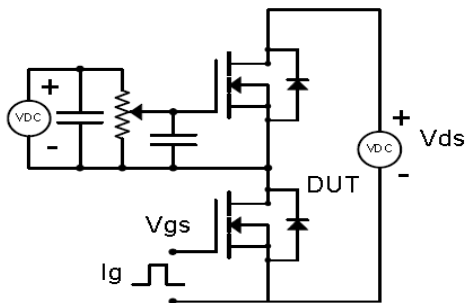


Fig 14: Max. Transient Thermal Impedance

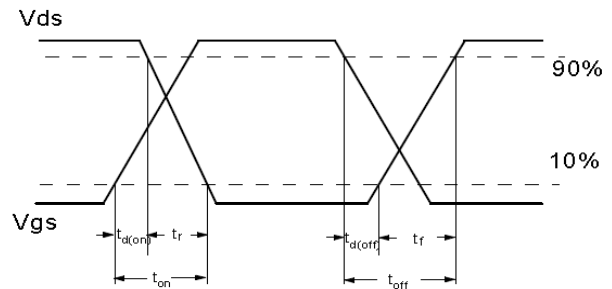
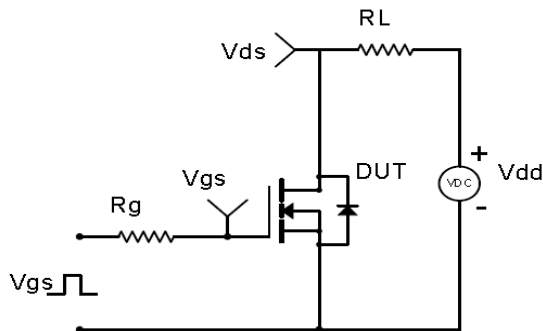


Test Circuit & Waveform

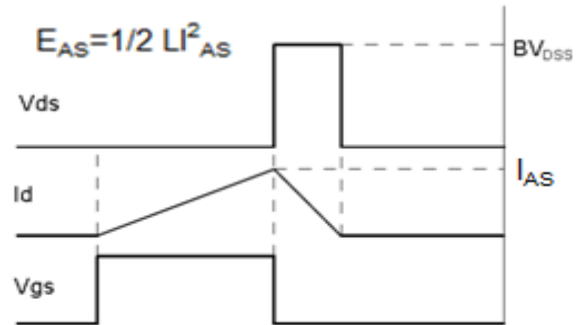
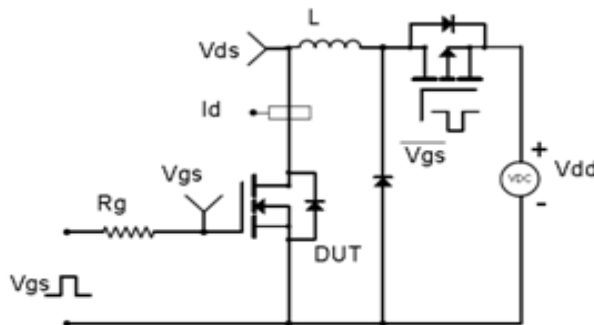
Gate Charge Test Circuit & Waveform



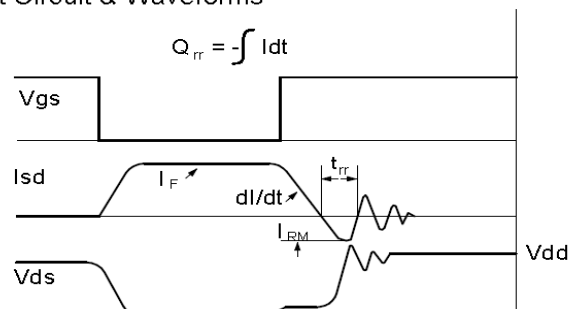
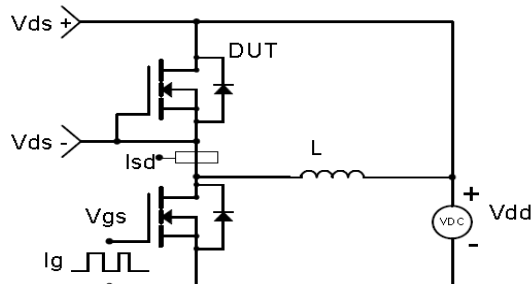
Resistive Switching Test Circuit & Waveforms



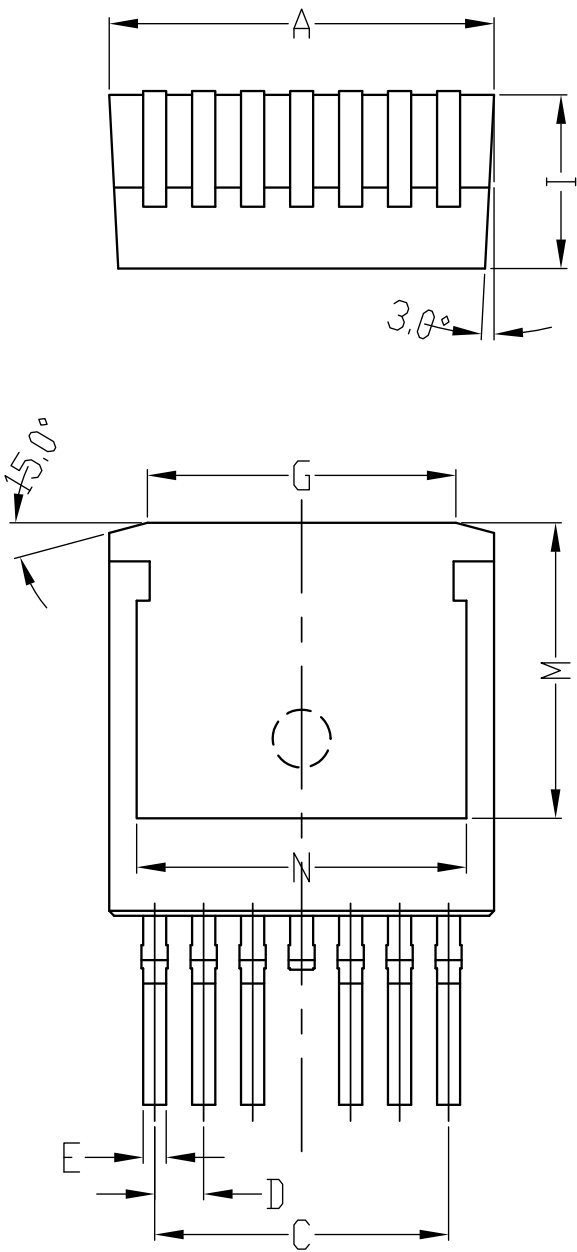
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Mechanical Dimensions for TO263-7L



Symbol	MM			Inch		
	Min	Mim	Max	Min	Mim	Max
A	9.88	9.98	10.08	0.3890	0.3929	0.3969
B	9.09	9.19	9.29	0.3579	0.3618	0.3657
C	7.54	7.62	7.70	0.2969	0.3000	0.3031
D	1.23	1.27	1.31	0.0484	0.0500	0.0516
E	0.55	0.6	0.65	0.0217	0.0236	0.0256
F	1.27	1.30	1.33	0.0500	0.0512	0.0524
G	7.7	8	8.3	0.3031	0.3150	0.3268
H1	-0.10	+0.10	+0.2	-0.0039	+0.0039	+0.0079
I	4.42	4.50	4.58	0.1740	0.1772	0.1803
L	4.60	4.90	5.20	0.1810	0.1930	0.2047
L1	1.05	1.15	1.25	0.0413	0.0453	0.0492
L2	1.66	1.76	1.86	0.0654	0.0693	0.0732
a	-7°	0°	7°	-7°	0°	7°
N	8.25	8.55	8.85	0.3248	0.3366	0.3484
M	7.36	7.66	7.96	0.2898	0.3055	0.3134

